

TSMC-02-189/03-856



April 16, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/796,430 03/09/04 |

Chin-Shan Hou et al.

A PLACEMENT AND ROUTING METHOD  
TO REDUCE JOULE HEATING

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on April 26, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephen B. Ackerman 4/26/04

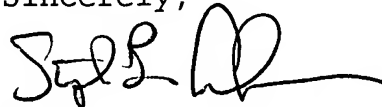
U.S. Patent 5,811,352 to Numata et al., "Method of Making Reliable Metal Leads in High Speed LSI Semiconductors Using Dummy Leads," describes a method to reduce Joule heating in metal lines.

U.S. Patent 5,510,293 to Numata, "Method of Making Reliable Metal Leads in High Speed LSI Semiconductors Using Thermoconductive Layers," discloses a method to reduce Joule heating in metal lines.

U.S. Patent 5,858,869 to Chen et al., "Method for Fabricating Intermetal Dielectric Insulation Using Anisotropic Plasma Oxides and Low Dielectric Constant Polymers," teaches a method to form an intermetal dielectric layer with improved Joule heating performance.

U.S. Patent 6,265,308 to Bronner et al., "Slotted Damascene Lines for Low Resistive Wiring Lines for Integrated Circuit," describes a method to form damascene lines and vias.

Sincerely,

A handwritten signature in black ink, appearing to read 'Stephen B. Ackerman', with a stylized flourish at the end.

Stephen B. Ackerman,  
Reg. No. 37761

# INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

APR 29 2004

U. S. PATENT DOCUMENTS

Docket Number (Optional)

TSMC-02-189/03-856

Application Number

10/796,430

Applicant

Chin-Shan Hou et al.

Filing Date

03/09/04

Group 1/1/1/1

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	TITLE	CLASS	SUBCLASS	PLUNG DATE IF APPROPRIATE
	5811352	9/22/98	Numata et al.	438	622	11/6/96
	5510293	4/23/96	Numata	437	195	5/31/94
	5858869	1/12/99	Chen et al.	438	597	6/3/97
	6265308	7/24/01	Bronner et al.	438	637	11/30/98

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)


EXAMINER

DATE COMPLETED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.